

ABSTRACT

The invention relates to a device and a method for applying semiconductor chips (5) to a plurality of carriers (4), especially smart card modules or flexboards. According to the invention, an adhesive application device (1) is used to apply an adhesive to pre-defined positions on the carrier (4), a fitting device (2) is used to apply the semiconductor chips (5) to the positions on the carrier (4), and a hardening device (3) is used to harden the adhesive. The hardening device (3) and/or another device can be connected to a conveyor belt (6) for transporting the carrier (4) along the devices, by means of a clamping device (13, 14), and can be displaced in the transport direction at the speed of the conveyor belt (6), by means of a lifting device (15).